

PRODUCT NO	DIM L	PLATING	RECOMMENDED P.C. BOARD THICKNESS	PRODUCT NO	PLATING
10022676-00ILF	2.70	NOTE 2	1.57mm (0.062") / 2.36mm (0.093")	10022676-001	NOTE 5
10022676-01ILF	3.70			10022676-011	

HOLE	A	REMARK
Hole Diameter after plating	0.45 - 0.55 mm	FOR -XXX & -XXXLF
Drilled hole	0.58 - 0.62 mm	
Copper plating	25 - 50 μm	
Sn Plating	5 - 15 μm	FOR -XXXLF ONLY
Sn-Pd Plating	5 - 15 μm	FOR -XXX ONLY

A

B

C

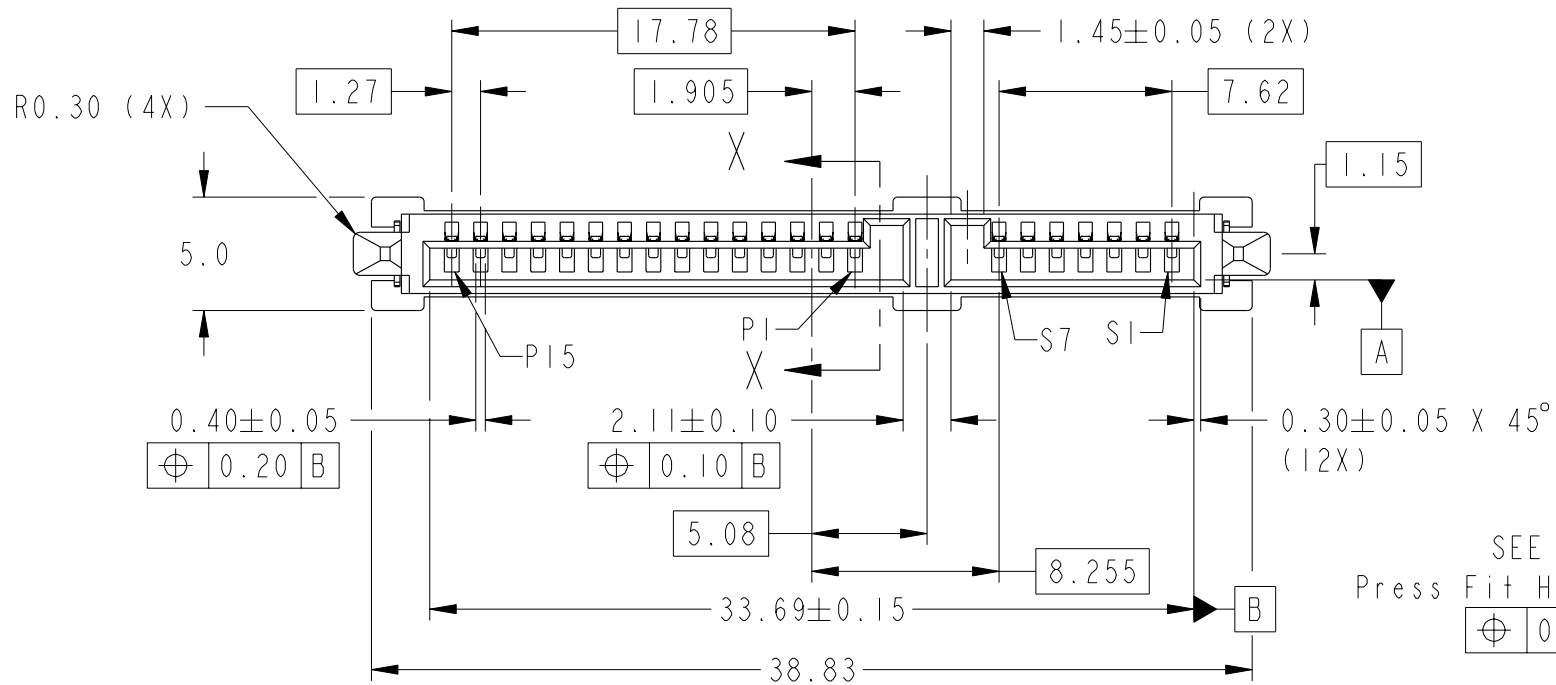
D

A

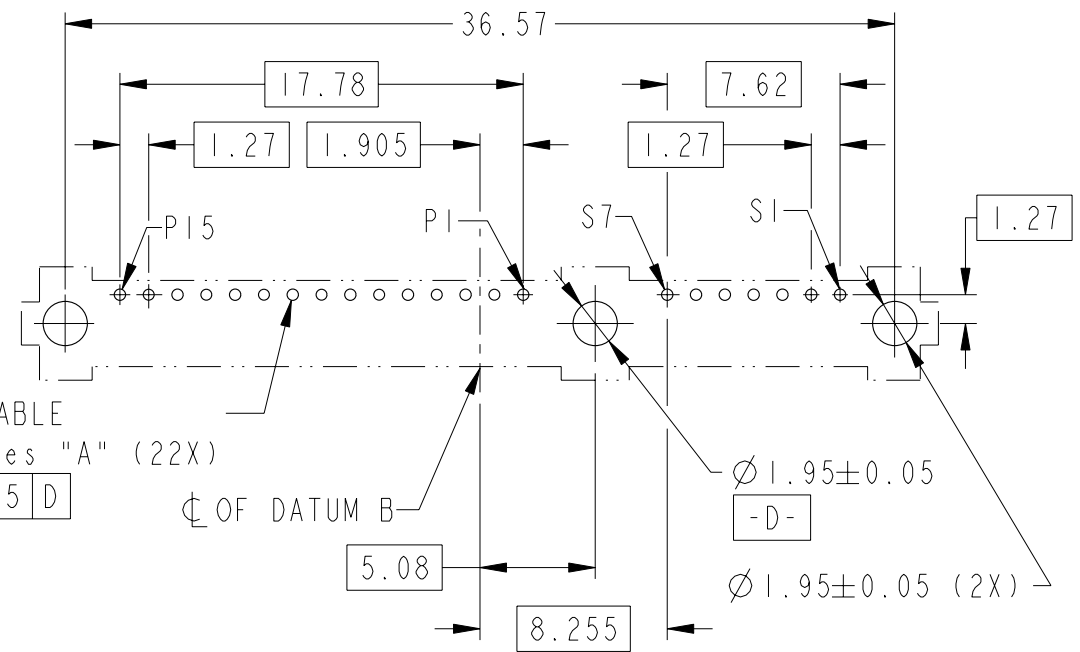
B

C

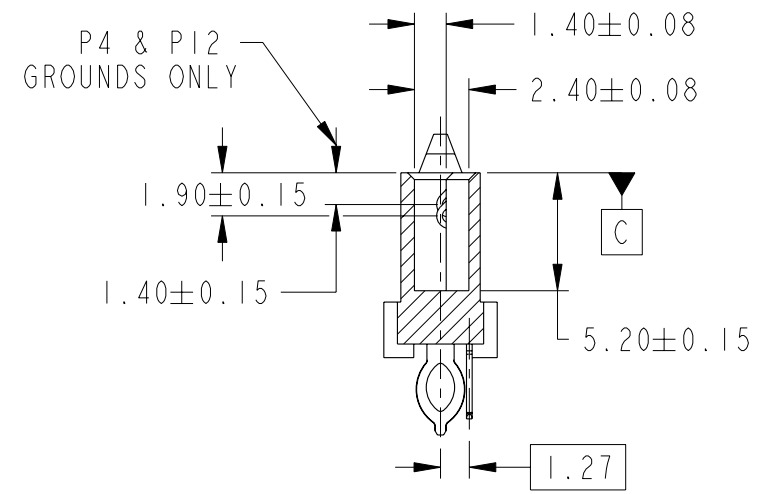
D



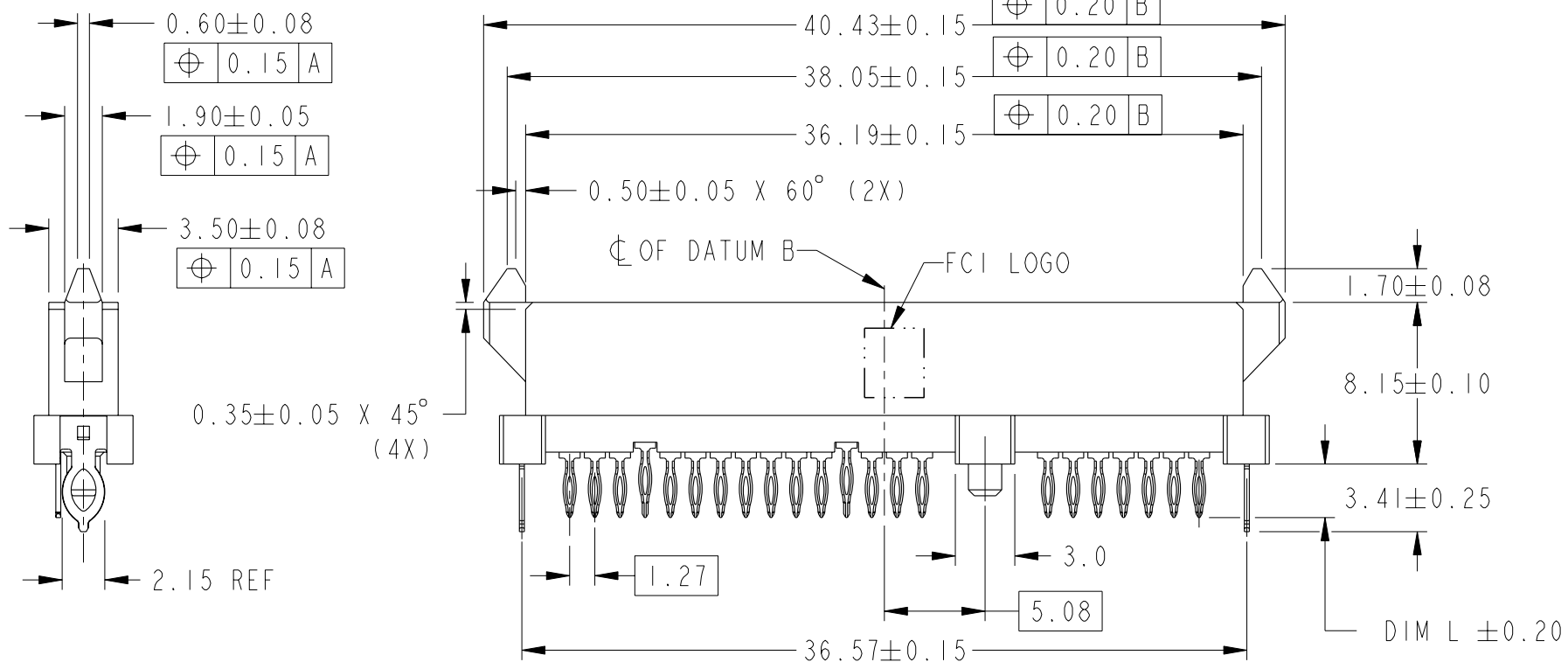
SEE TABLE  
Press Fit Holes "A" (22X)  
 $\varnothing$  0.05 D



**RECOMMENDED P.C.B. LAYOUT**

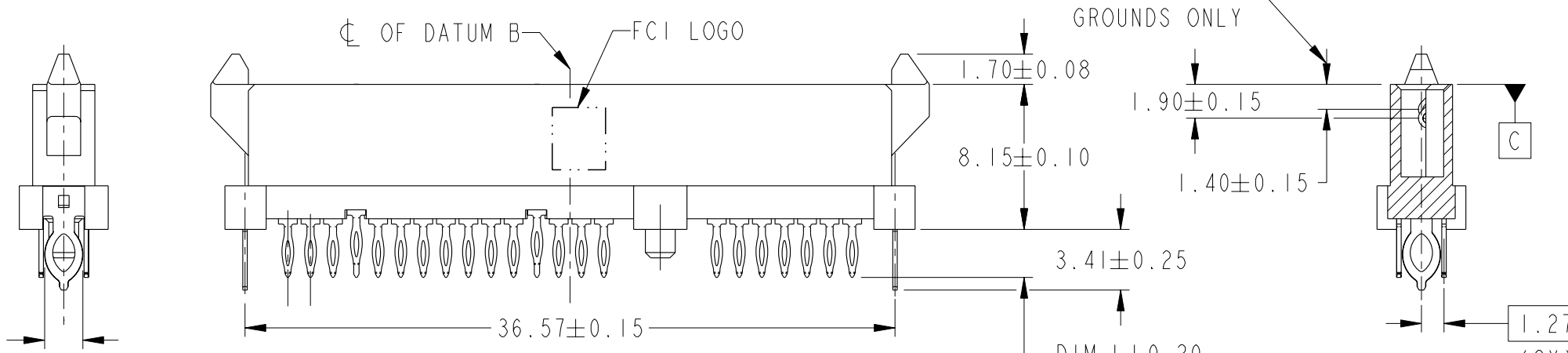
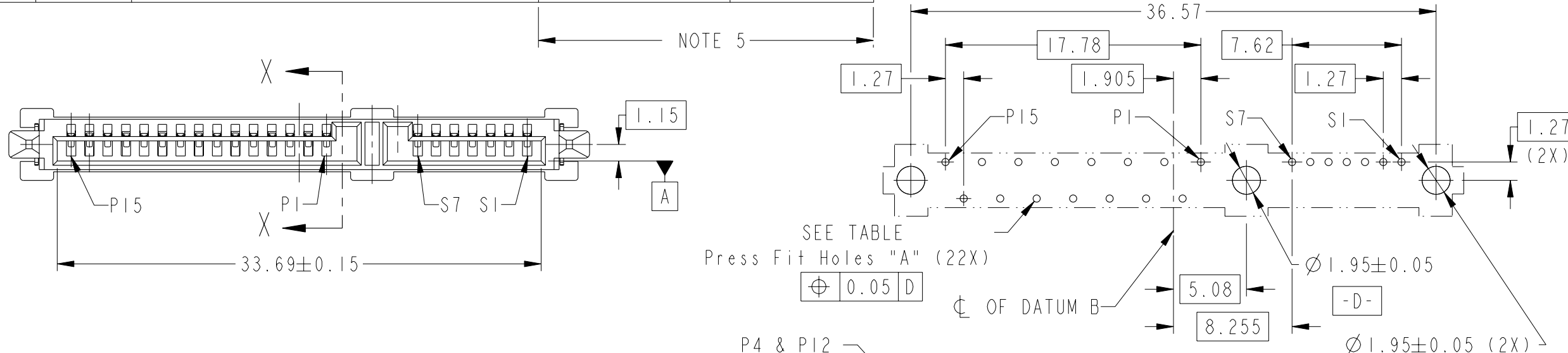


**SECTION X-X**



spec ref	-	dr	GL LOO	2004-10-05	projection	MM	size	A3	scale	3:1
tolerance std	ISO 406 ISO 1101	eng	GL LOO	2004-10-05			ecn no	S10-0228	rel level	-
	TOLERANCES UNLESS OTHERWISE SPECIFIED	chr	GL LOO	2010-10-28						
surface	ISO 1302	appr	JOEY NG	2010-10-28	product family	S-ATA				
	linear	0.X	± -		S-ATA COMB RECEP. VERTICAL PF TYPE ASSY		dwg no	10022676		rev
		0.XX	±0.20							
		0.XXX	± -							
	angular	0°	±2°	www.fci.com	cat. no.	-	Product - Customer Drw		sheet 1 of 2	

PRODUCT NO	DIM L	PLATING	RECOMMENDED P.C. BOARD THICKNESS	PRODUCT NO	PLATING
10022676-002LF	2.70	NOTE 2	1.57mm (0.062") / 2.36mm (0.093")	10022676-002	NOTE 5
10022676-012LF	3.70		2.36mm (0.093")	10022676-012	



RECOMMENDED P.C.B. LAYOUT

NOTES:

- MATERIAL:
  - HOUSING : HIGH TEMP, THERMOPLASTIC, UL 94V-0  
COLOR : BLACK
  - TERMINAL : COPPER ALLOY
  - HOLD DOWN : COPPER ALLOY
- FINISH : FOR XXXXXXXX-XXXLF
  - TERMINAL : 30μ" Au PLATING (CONTACT POINT) OVER 50μ" MIN NICKEL
  - SOLDER TAIL : 20μ" MIN-60μ" MAX TIN OVER 50μ" MIN NICKEL
  - HOLD DOWN : 50μ" MIN TIN OVER 50μ" MIN NICKEL
- TRUE POSITION NOTES APPLY AT (L= 2.70MM) TERMINAL TIP
- PER S-ATA SPEC REV 1.0a
- FINISH : FOR XXXXXXXX-XXX
  - TERMINAL : 30μ" Au PLATING (CONTACT POINT) OVER 50μ" MIN NICKEL
  - SOLDER TAIL : 20μ" MIN-60μ" MAX TIN-LEAD OVER 50μ" MIN NICKEL
  - HOLD DOWN : 50μ" MIN TIN-LEAD OVER 50μ" MIN NICKEL
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN CONVECTION, INFRA-RED OR VAPOR PHASE REFFLOW OVEN
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- PART NUMBERS ENDING IN "LF" MEANS FOR NOTE 7 LEAD FREE IDENTIFICATION
- A  $\Delta$  F SYMBOL WILL BE NEXT TO ANY DIMENSION, VIEW, OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION.
- THE STD PACKAGING IS IN TRAY.
- NOTE 7 AND 8 DO NOT APPLY TO TIN LEAD PLATING P/N XXXXXXXX-XXX IN TABLE.

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- FINISH : FOR XXXXXXXX-XXX
  - TERMINAL : 30μ" Au PLATING (CONTACT POINT) OVER 50μ" MIN NICKEL
  - SOLDER TAIL : 20μ" MIN-60μ" MAX TIN-LEAD OVER 50μ" MIN NICKEL
  - HOLD DOWN : 50μ" MIN TIN-LEAD OVER 50μ" MIN NICKEL

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surface	<table border="1"> <tr> <td>linear</td> <td>0.X</td> <td>±</td> <td>-</td> </tr> <tr> <td></td> <td>0.XX</td> <td>±0.20</td> <td></td> </tr> <tr> <td></td> <td>0.XXX</td> <td>±</td> <td>-</td> </tr> <tr> <td>angular</td> <td>0°</td> <td>±2°</td> <td></td> </tr> </table>	linear	0.X	±	-		0.XX	±0.20			0.XXX	±	-	angular	0°	±2°		appr	JOEY NG	2010-10-28	S-ATA		rel level	-
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www.fci.com		cat. no.	-		Product - Customer Drw		sheet 2 of 2																	